Triacs

Silicon Bidirectional Thyristors

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

Features

- Blocking Voltage to 800 V
- On-State Current Rating of 12 Amperes RMS at 85°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt 100 V/\u00fcs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dI/dt 6.0 A/ms minimum at 125°C
- Internally Isolated (2500 V_{RMS})
- N Indicates UL Registered File #E69369
- These are Pb-Free Devices

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (T _J = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V _{DRM,} V _{RRM}		V
BTA12-600C4G BTA12-800C4G		600 800	
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T _C = 85°C)	I _{T(RMS)}	12	Α
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T _C = 25°C)	I _{TSM}	120	Α
Circuit Fusing Consideration (t = 8.3 ms)	l ² t	40	A ² sec
Peak Gate Current ($T_J = 125^{\circ}C$, $t = 20\mu s$)	I _{GM}	2.0	Α
Peak Gate Power (Pulse Width \leq 1.0 μ s, T _C = 80°C)	P _{GM}	20	W
Average Gate Power (T _J = 125°C)	P _{G(AV)}	1.0	W
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C
RMS Isolation Voltage (t = 300 ms, R.H. \leq 30%, T _A = 25°C)	V _{iso}	2500	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

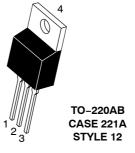


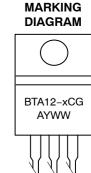
ON Semiconductor®

http://onsemi.com

TRIACS 12 AMPERES RMS 600 thru 800 VOLTS







x = 6 or 8
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

PIN ASSIGNMENT		
1	Main Terminal 1	
2	Main Terminal 2	
3	Gate	
4	No Connection	

ORDERING INFORMATION

Device	Package	Shipping		
BTA12-600C4G	TO-220AB (Pb-Free)	50 Units / Rail		
BTA12-800C4G	TO-220AB (Pb-Free)	50 Units / Rail		

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL CHARACTERISTICS

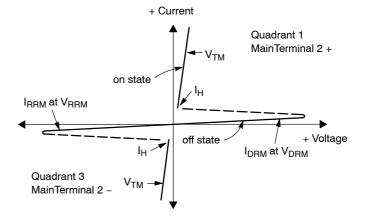
Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (AC) Junction-to-Ambient	$R_{ hetaJC} \ R_{ hetaJA}$	2.5 60	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 seconds	T _L	260	°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted; Electricals apply in both directions)

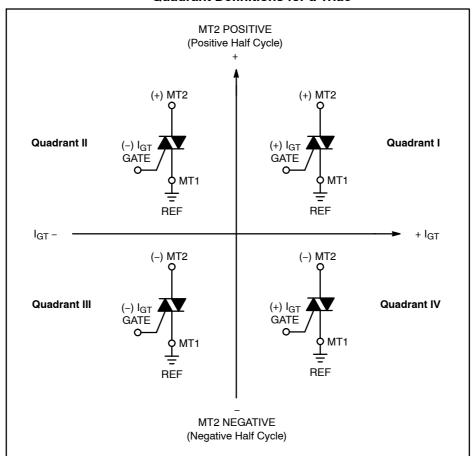
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				I.	
$\label{eq:peak_repetitive_Blocking_Current} Peak Repetitive Blocking Current \\ (V_D = Rated V_{DRM}, V_{RRM}; Gate Open) \\ T_J = 25^{\circ}C \\ T_J = +125^{\circ}C$	I _{DRM} , I _{RRM}	- -	- -	5.0 2.0	μA mA
ON CHARACTERISTICS	•	•	•		•
Peak On-State Voltage $I_{TM} = \pm 17$ A Peak; Pulse Width = 1 to 2 ms, Duty Cycle $\leq 2\%$	V _{TM}	-	_	1.55	V
Gate Trigger Current (Continuous dc) (Main Terminal Voltage = 12 Vdc, R_L = 30 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) MT2(-), G(+)	I _{GT}	- - - -	- - - -	25 25 25 25 50	mA
Latching Current (V_D = 12 V, I_G = 60 mA, I_{G4} = 120 mA) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) MT2(-), G(+)	ΙL	- - - -	- - - -	40 40 80 40	mA
Gate Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 Vdc, R_L = 30 Ω) MT2(+), G (+) MT2(+), G (-) MT2(-), G (-) MT2(-), G (-)	V _{GT}	- - - -	- - - -	1.3 1.3 1.3 1.3	V
Gate Non–Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 V, R_L = 30 Ω , T_J = +125°C) All Four Quadrants	V _{GD}	0.2	-	-	V
Holding Current ($V_D = 12 \text{ Vdc}$, Gate Open, Initiating Current = $\pm 200 \text{ mA}$)	I _H	-	-	25	mA
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Commutation Current (T _C = +125°C)	di/dt _(c)	6.0	-	_	A/ms
Critical Rate of Rise of Off-State Voltage (V_D = Rated V_{DRM} , Exponential Voltage Rise, Gate Open, T_C = +125°C)	dv/dt	100	_	-	V/µs

Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V _{DRM}	Peak Repetitive Forward Off State Voltage
I _{DRM}	Peak Forward Blocking Current
V _{RRM}	Peak Repetitive Reverse Off State Voltage
I _{RRM}	Peak Reverse Blocking Current
V _{TM}	Maximum On State Voltage
I _H	Holding Current



Quadrant Definitions for a Triac



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

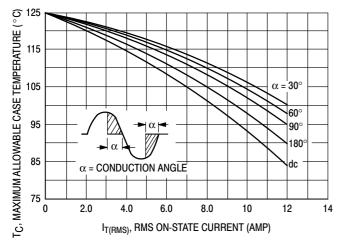


Figure 1. Current Derating

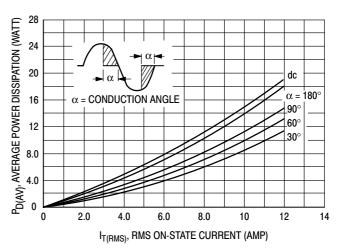


Figure 2. Power Dissipation

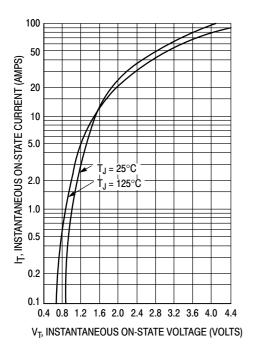


Figure 3. Maximum On-State Voltage Characteristics

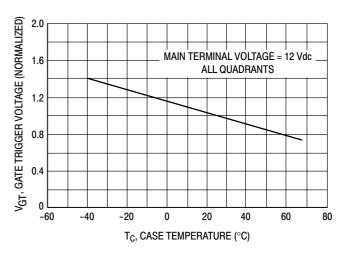
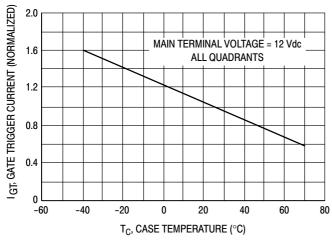


Figure 4. Typical Gate Trigger Voltage



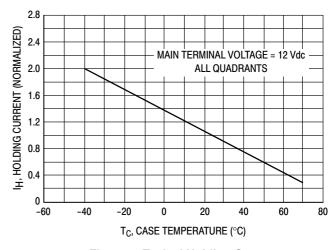


Figure 5. Typical Gate Trigger Current

Figure 6. Typical Holding Current

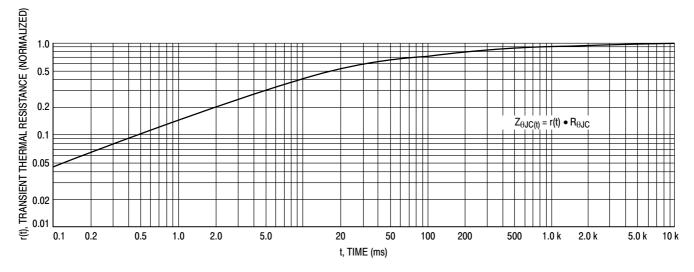
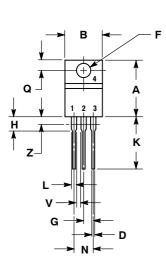
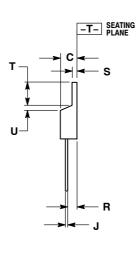


Figure 7. Thermal Response

PACKAGE DIMENSIONS

TO-220 CASE 221A-07 **ISSUE AA**





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2 04

STYLE 12:

- PIN 1. MAIN TERMINAL 1
 - 2. MAIN TERMINAL 2
 - GATE
 - 4. NOT CONNECTED

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